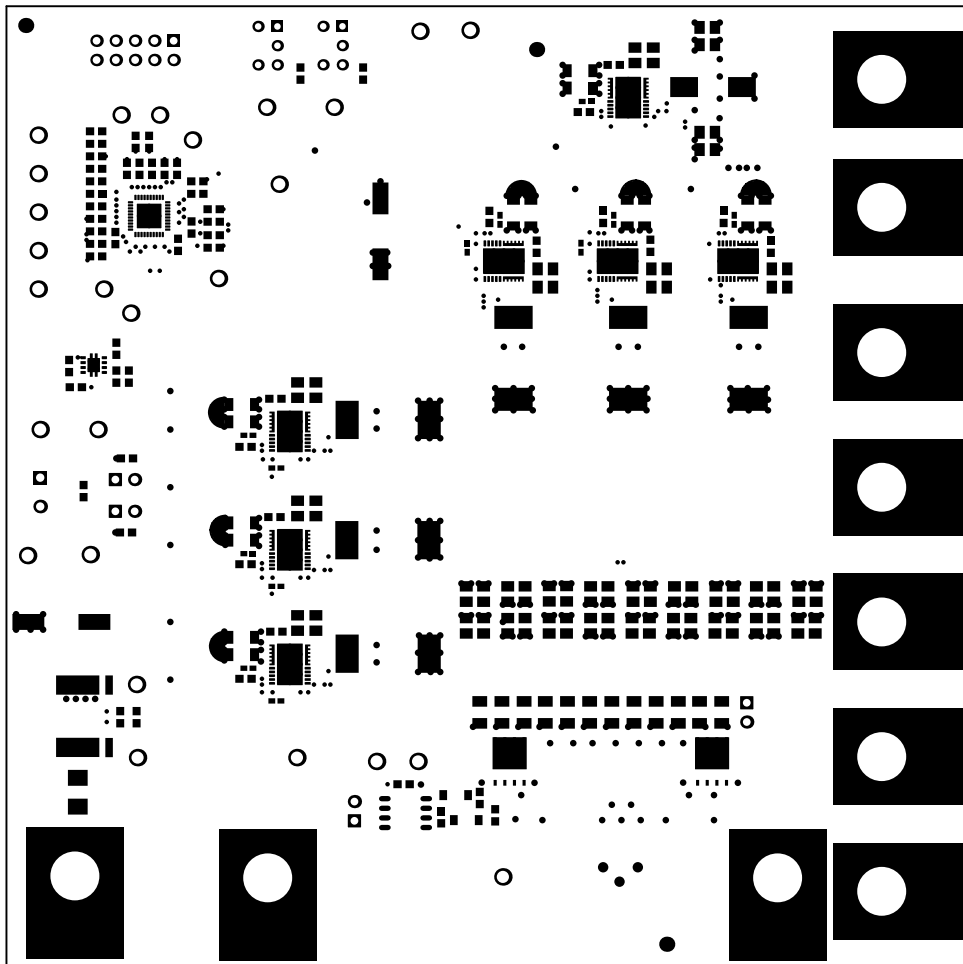
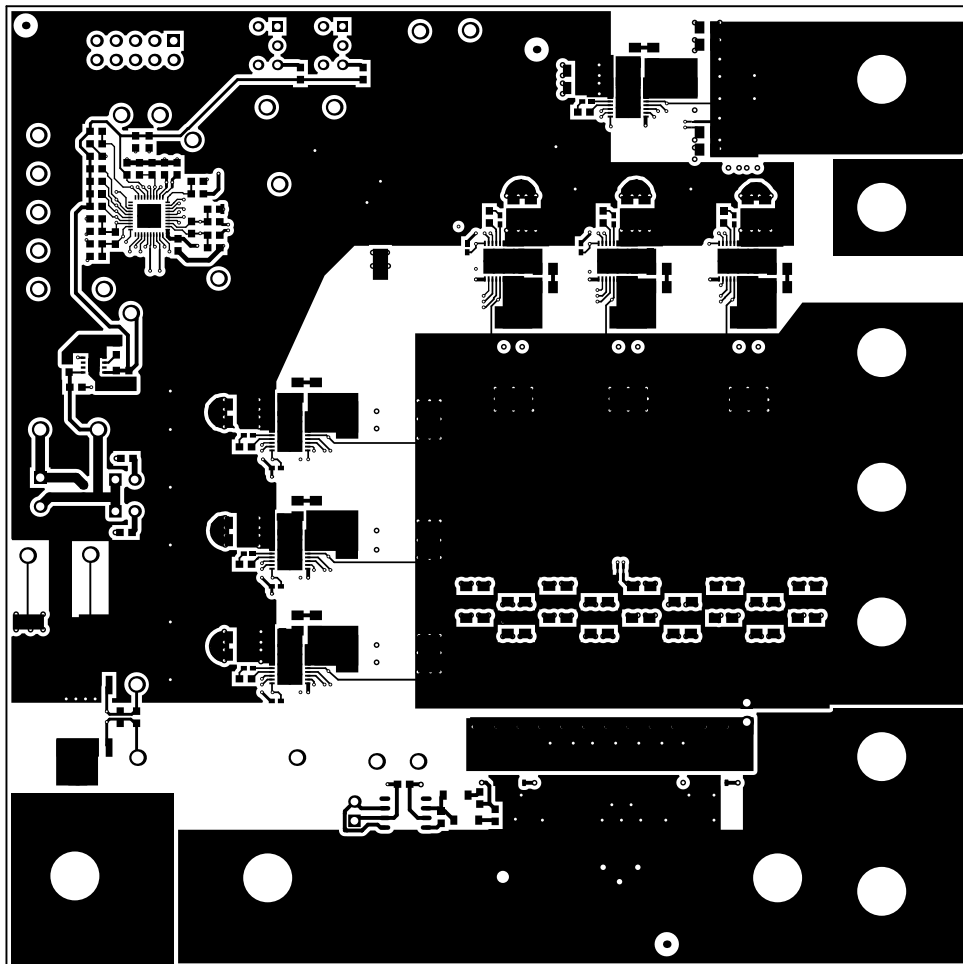


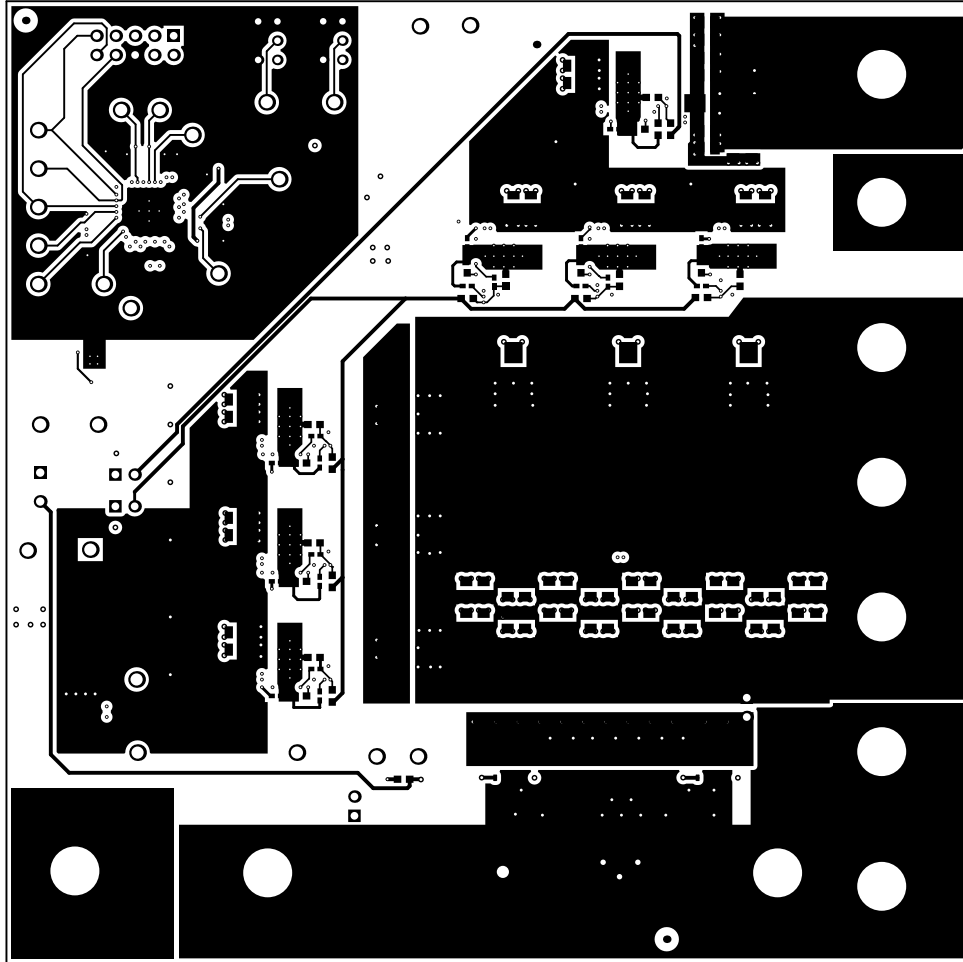
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01367	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 8/14/2017	8:49:53 AM	TEXAS INSTRUMENTS



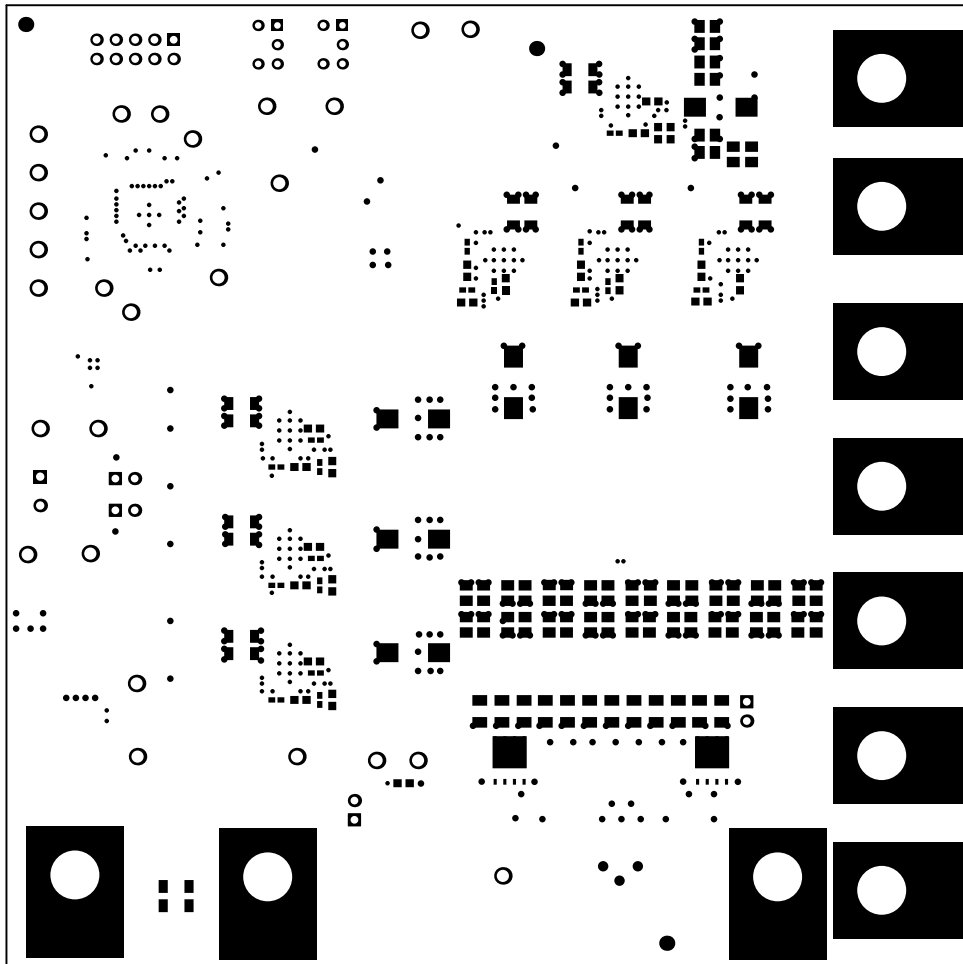
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01367	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 8/14/2017 8:49:54 AM	TEXAS INSTRUMENTS	



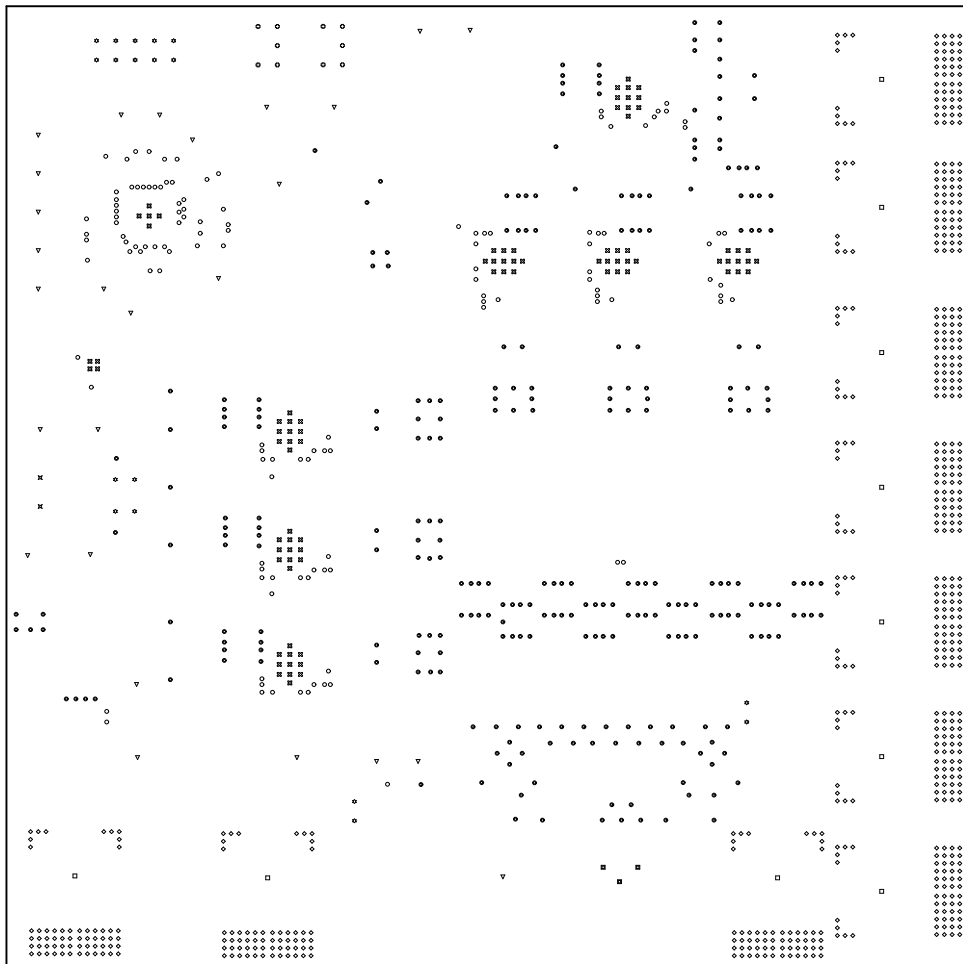
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01367	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 8/14/2017 8:49:56 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01367	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 8/14/2017 8:49:58 AM	TEXAS INSTRUMENTS	

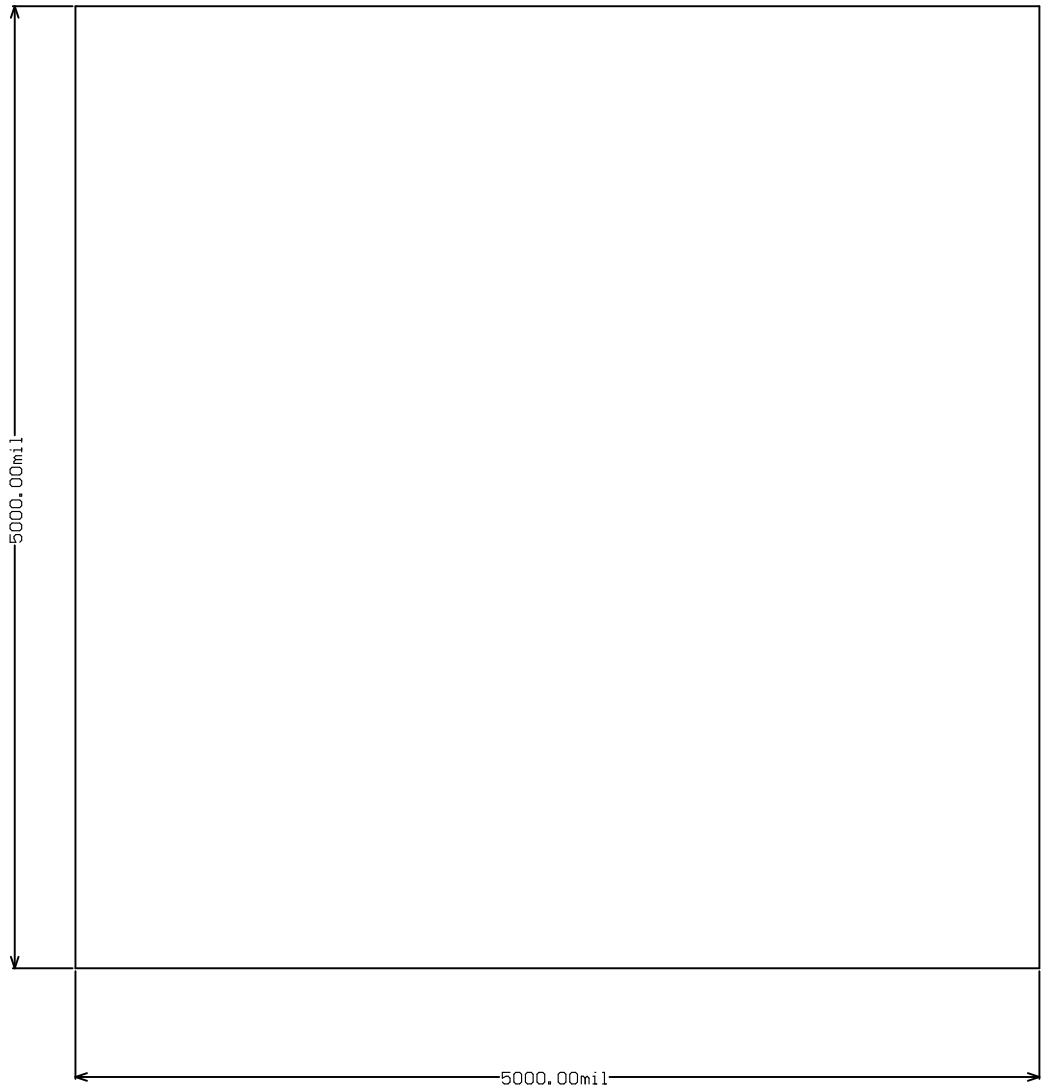


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01367	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/14/2017 8:49:59 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	86	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	128	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
●	281	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
◇	580	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
■	3	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	10	35.04mil (0.890mm)	PTH	Round	Top Layer - Bottom Layer	
☆	18	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
▽	26	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
□	10	254.00mil (6.452mm)	PTH	Round	Top Layer - Bottom Layer	
	1144 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01367	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 8/14/2017	8:50:02 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01367	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 8/14/2017 8:50:05 AM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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